

Description

The SI2309 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge .This device is well suited for use as a load switch or in PWM applications.

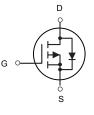
General Features

Application

Load switch PWM application







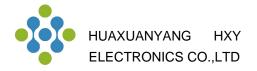
P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
SI2309	SOT-23	N9ADE	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
Vds	Drain-Source Voltage	-60	V
Vgs	Gate-Source Voltage	±20	V
Ι _D	Drain Current-Continuous	-2	A
Ідм	Drain Current-Pulsed (Note 1)	-8	A
PD	Maximum Power Dissipation	1.5	W
Тј,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	°C
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	83.3	°C/W



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	· · ·					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250µA -60		-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1.4	-2.0	-2.6	V
Durain Courses On State Desintenes	P	V _{GS} =-10V, I _D =-1.5A	-	140	160	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-1.5A	-	160	200	mΩ
Forward Transconductance	g fs	V _{DS} =-5V,I _D =-1.5A	-	3	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C _{lss}		-	444.2	-	PF
Output Capacitance	C _{oss}	V_{DS} =-30V, V_{GS} =0V,	-	19.6	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	17.9	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	40	-	nS
Turn-on Rise Time	tr	V_{DD} =-30V, I _D =-1.5A,	-	35	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V,R _G =3Ω	-	15	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg		-	11.3	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-30,I _D =-1.5A,	-	2.7	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =-10V	-	1.6	-	nC
Drain-Source Diode Characteristics	I					•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-1.5A	-		-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-1.6	А
Reverse Recovery Time	t _{rr}	TJ = 25°C, I _F = - 1.5A	-	25		nS
Reverse Recovery Charge	Qrr	di/dt = -100A/µs ^(Note3)	-	31		nC

Electrical Characteristics (T_c=25°C unless otherwise noted)

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

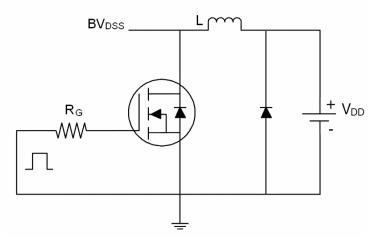
3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production

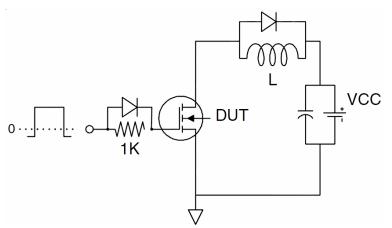


Test Circuit

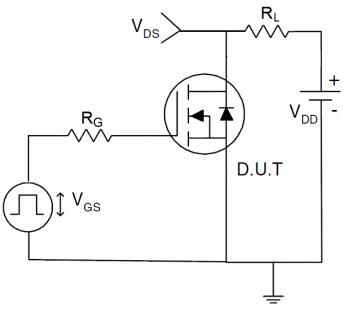
1) E_{AS} test Circuit



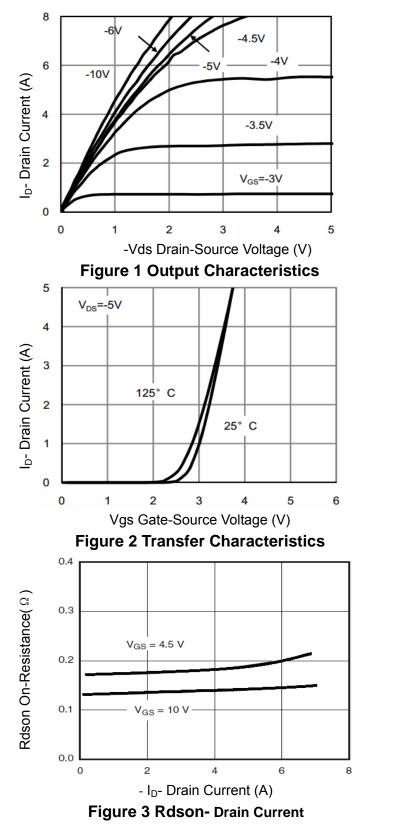
2) Gate charge test Circuit



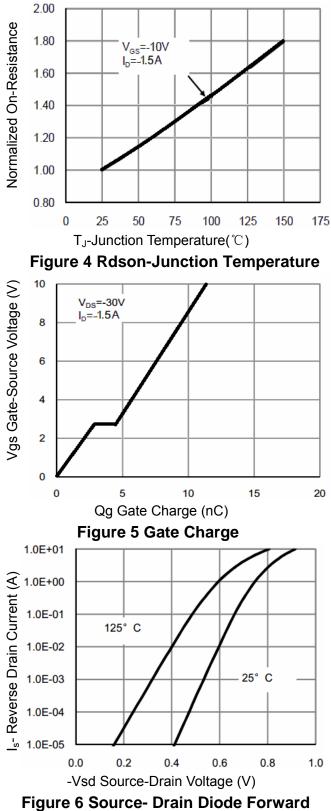
3) Switch Time Test Circuit



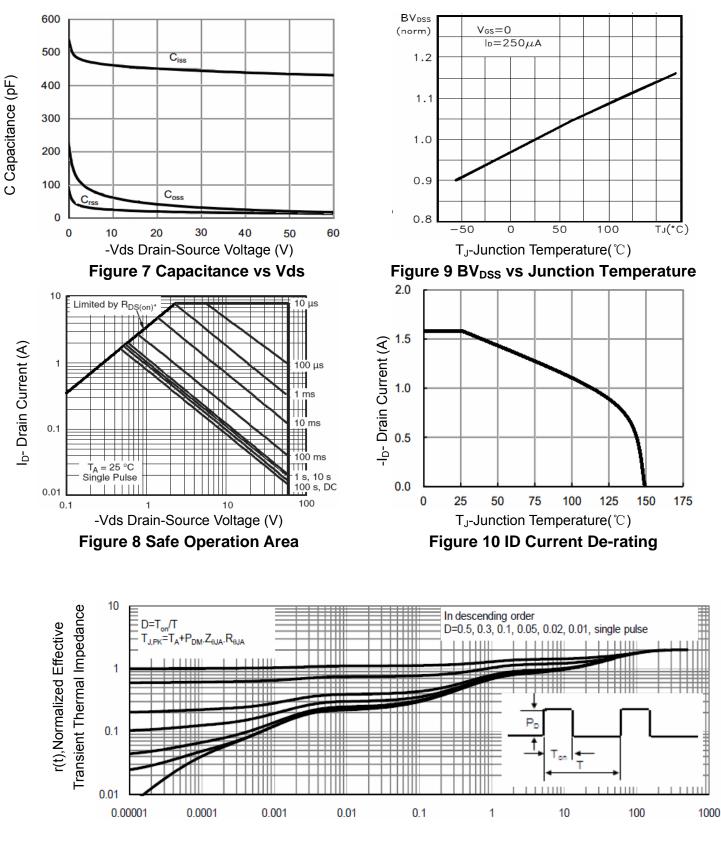


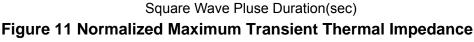


Typical Electrical and Thermal Characteristics (Curves)



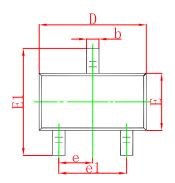


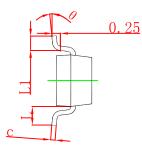


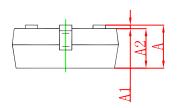




SOT-23 Package Outline Dimensions

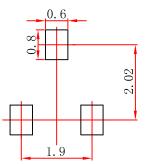






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters. 2.General tolerance:±0.05mm. 3.The pad layout is for reference purposes only.



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